

LTM8026 81LD -BGA -Pb 15mm X 11.25mm X 3.42mm - SOLDER DA (TABLE OF MATERIAL DECLARATION)

Contains > 1000ppm of Lead in the terminations

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.1904	Barium Compounds	7727-43-7	0.00518	2.72
				Bismaleimide/Triazine/Resin/Filler Substance(Silica Crystalline)	105391-33-1,1156-51-0/9003-36-5/21645-51-2	0.03485	18.31
				Copper Metal	7440-50-8	0.12590	66.14
				Copper Compounds	1328-53-6	0.00005	0.02
				Ecotoxic substances	7440-38-2, 7440-28-0	0.00003	0.02
				Gold metal or alloy	7440-57-5	0.00059	0.31
				Nickel	7440-02-0	0.00381	2.00
				Zinc	7440-66-6	0.00030	0.16
				Continuous Filament Fiber Glass	65997-17-3	0.01892	9.94
				Chromium(III) Oxide	1308-38-9	0.00001	0.01
				Silica amorphous	7631-86-9	0.00011	0.06
				Talc;not containing fibers like asbestos	14807-96-9	0.00059	0.31
				Cyanoguanidine	461-58-5	0.00002	0.01
				Calcium caobonate	471-34-1	0.00001	0.00
2	Solder Paste	Alloy	0.0302	Sn	7440-31-5	0.02869	95.00
				Sb	7440-36-0	0.00151	5.00
4	Passive/Active Components		0.5162	Iron Powder (Fe)	7439-89-6	0.28653	55.51
				Copper (Cu)	7440-50-8	0.17996	34.86
				Nickel (Ni)	7440-02-0	0.00684	1.33
				Tin (Sn)	7440-31-5	0.00232	0.45
				Ceramic (Ba compounds)	12047-27-7	0.04055	7.86
5	Active lcs	Silicon	0.0066	Silicon	7440-21-3	0.00655	100.00
6	Wire	Gold	0.0007	Au	7440-57-5	0.00070	99.99
6	Solder Ball	63Sn/37Pb	0.1548	Sn	7440-31-5	0.09752	63.00
				Pb	7439-92-1	0.05728	37.00
8	Encapsulation	Epoxy Resin	0.6364	Fused Silica	60676-86-0	0.49126	77.20
				Epoxy Resin	non-disclosure	0.05664	8.90
				Phenol Resin	non-disclosure	0.05664	8.90
				Crytalline Silica	14808-60-7	0.01909	3.00
				Carbon Black	1333-86-4	0.00318	0.50
				Metal Hydroxide	non-disclosure	0.00955	1.50
Total Package Weight			1.5351				

Note: Composition derived from MSDS and material C of C from Vendors
Component Weight based on assembly of generic parts